Celanese
The chemistry inside innovation™

HOSTAFORM® C 2521 LS

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POM copolymer

Stiff-flowing type for injection molding and extrusion with high impact toughness and good tracking resistance over a high range of temperature; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. This grade has been specially stabilized to prevent discoloration and deterioration of mechanical properties from ultraviolet light exposure. The material is available in natural, black and colored.

Burning rate ISO 3795 and FMVSS 302 < 75 mm/min for a thickness more than 1 mm.

Ranges of applications: injection molding thick-walled, void-free molded parts; extrusion e.g. for boards and pipes.

FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	2.5	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.1	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2600	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	62	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	32	%	ISO 527-1/-2
Flexural modulus	2500	MPa	ISO 178
Tensile creep modulus, 1h	2300	MPa	ISO 899-1
Tensile creep modulus, 1000h	1100	MPa	ISO 899-1
Charpy impact strength, 23°C	250[P]	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	250	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	8.5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	7	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	144	MPa	ISO 2039-1
Poisson's ratio	0.38[C]		

[P]: Partial Break

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	165	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	101	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110	E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Specific heat capacity of melt	2210	J/(kg K)	ISO 22007-4

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Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	15	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	35	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1410	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	140	°C

Characteristics

Processing	Injection Moulding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	U.V. stabilised or stable to weather

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

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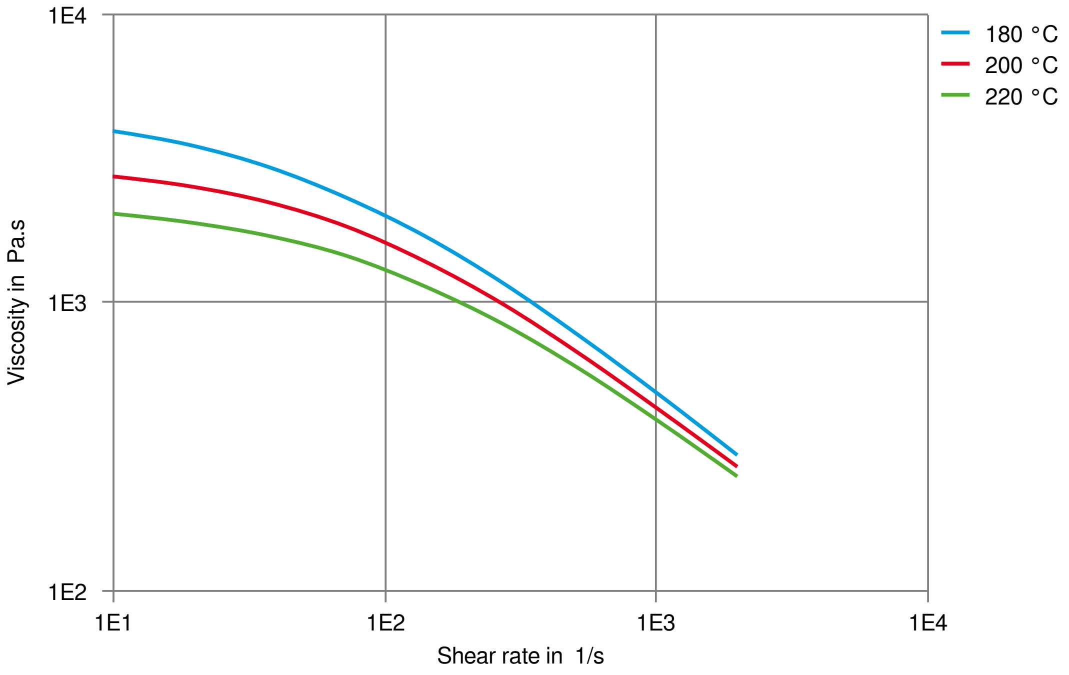
Viscosity-shear rate



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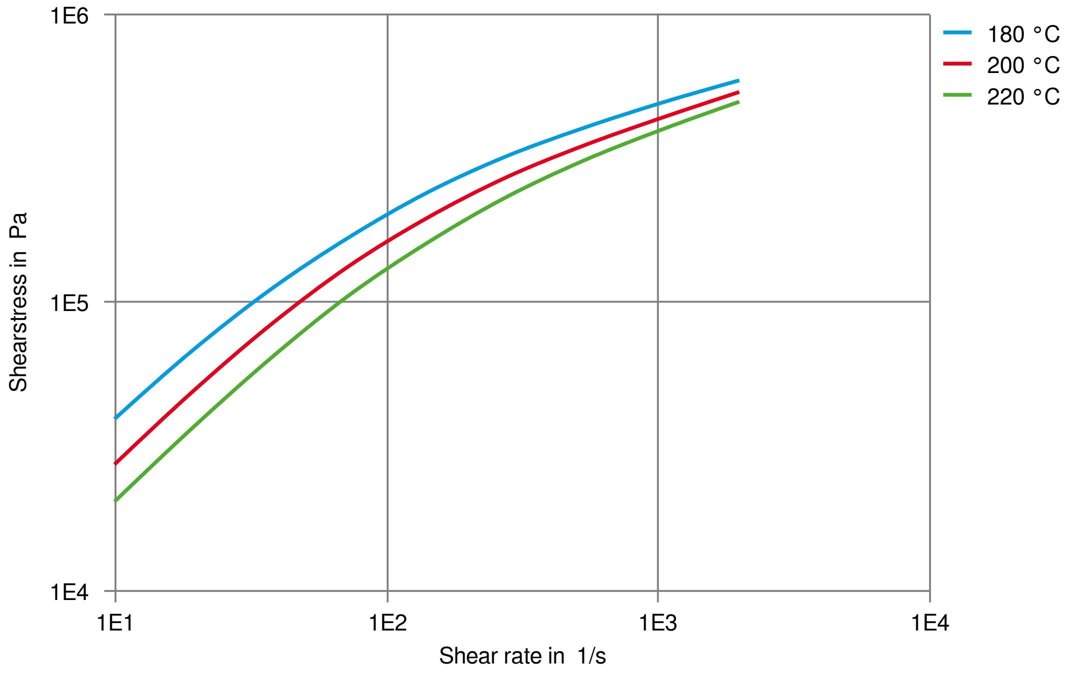
Shearstress-shear rate



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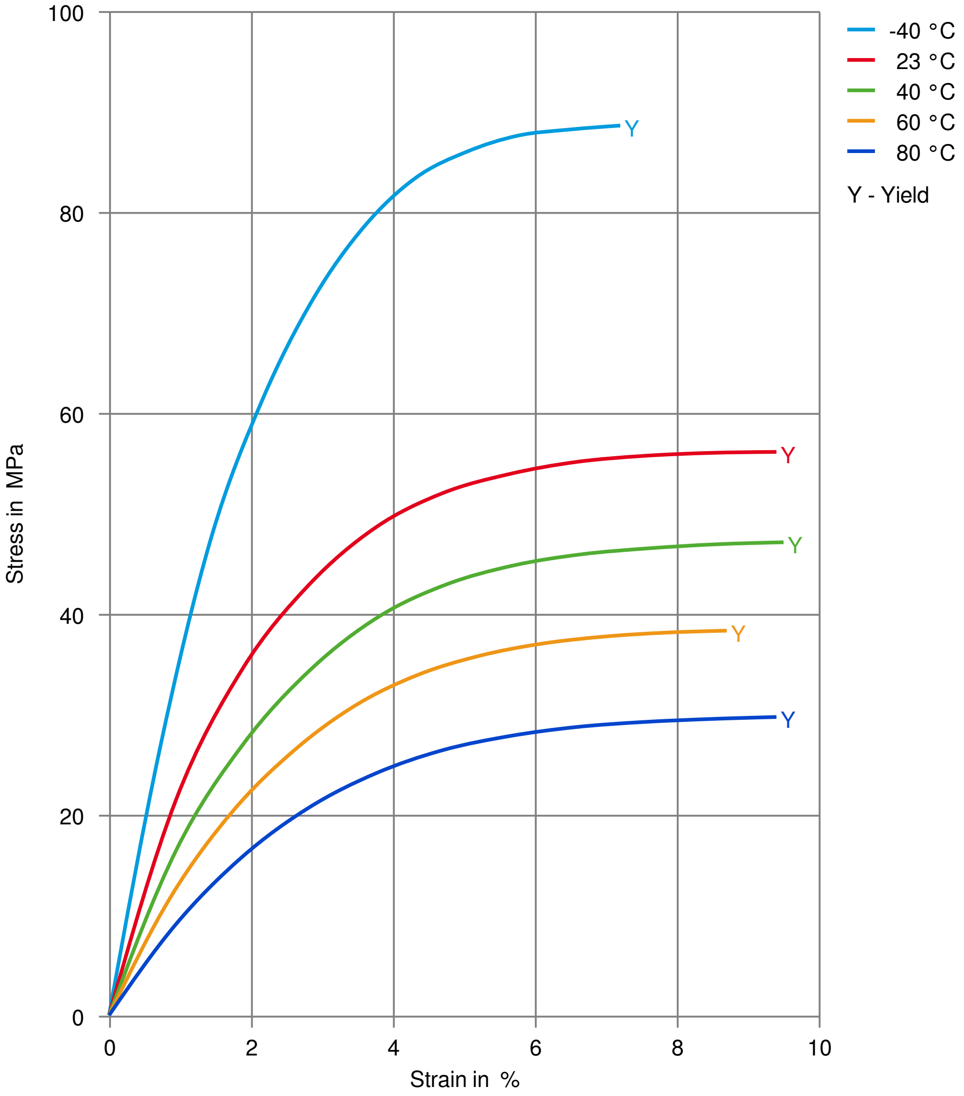
Stress-strain



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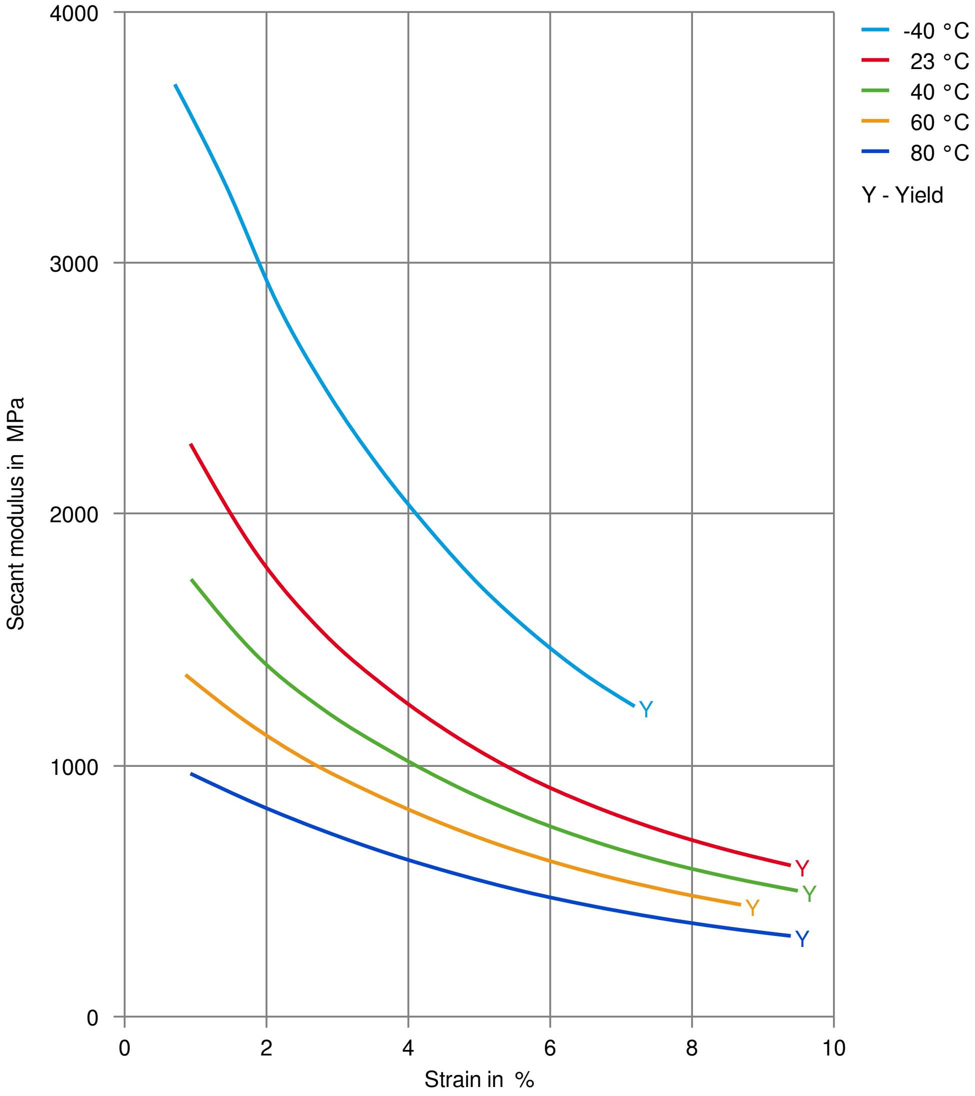
Secant modulus-strain



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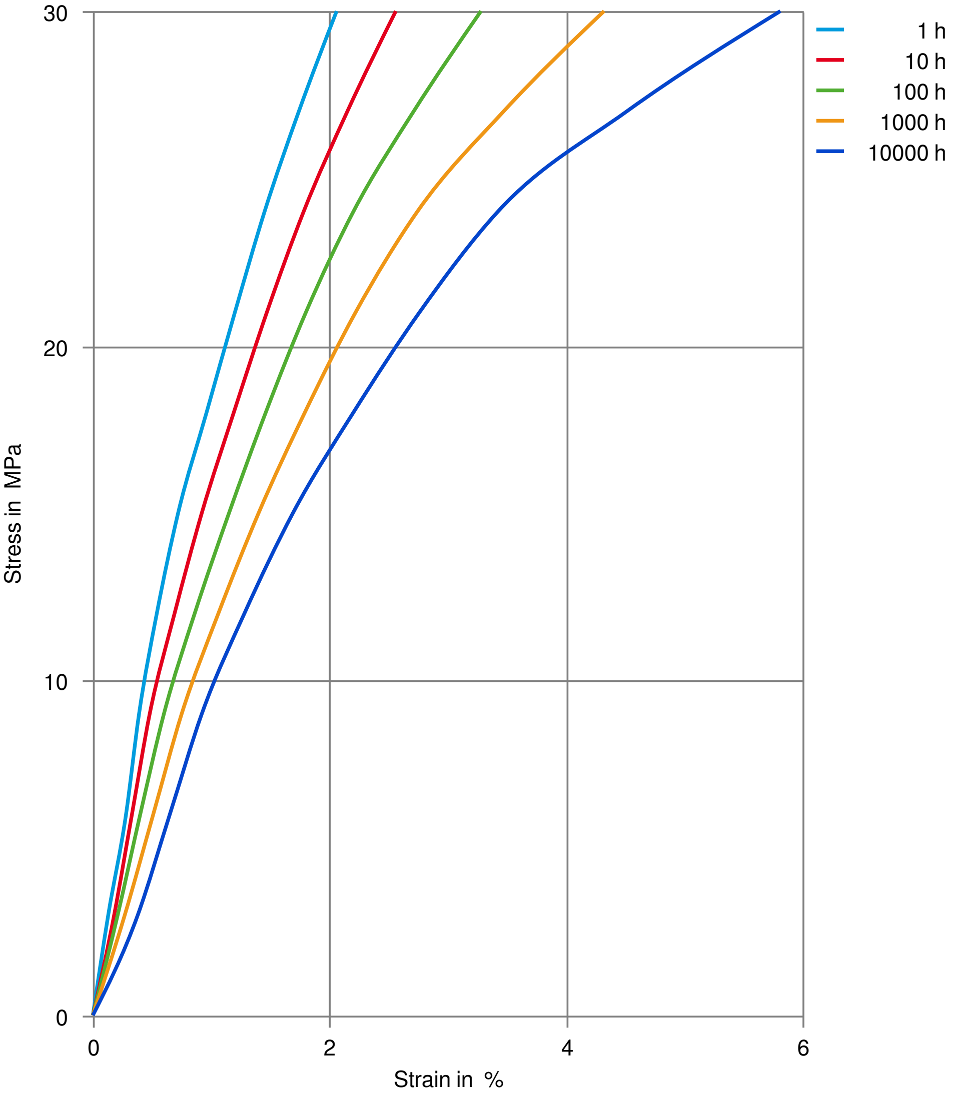
Stress-strain (isochronous) 23 °C



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Creep modulus-time 23 °C